

## Product Change Notification - KSRA-14QOCR585

**Date:** 17 Aug 2017  
**Product Category:** 8-bit PIC Microcontrollers  
**Notification subject:** CCB 2976 Final Notice: Qualification palladium coated copper (PdCu) bond wire for selected Atmel products available in 100L TFBGA package (9x9mm) at LPI assembly site.  
**Notification text:** **PCN Status:**  
 Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification palladium coated copper (PdCu) bond wire for selected Atmel products available in 100L TFBGA package (9x9mm) at LPI assembly site.

**Pre Change:**

Using gold (Au) bond wire

**Post Change:**

Using palladium coated copper (PdCu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	LPI assembly site	LPI assembly site
<b>Wire material</b>	Au wire	PdCu wire
<b>Die attach material</b>	2100A	2100A
<b>Molding compound material</b>	G770H	G770H
<b>Substrate material</b>	BT Resin substrate	BT Resin substrate

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity and qualifying palladium coated copper (PdCu) bond wire

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

September 18, 2017 (date code: 1738)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	August 2017	September 2017

Workweek	31	32	33	34	35	36	37	38	39
Qual Report Availability			X						
Final PCN Issue Date			X						
Implementation Date								X	

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**August 18, 2017:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_KSRA-14QOCR585\\_Affected CPN.pdf](#)
  - [PCN\\_KSRA-14QOCR585\\_Qual Report.pdf](#)
  - [PCN\\_KSRA-14QOCR585\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

<b>PCN_KSRA-14QOCR585</b>
<b>CATALOG_PART_NBR</b>
ATMEGA1280-16CU
ATMEGA1280-16CUR
ATMEGA1280V-8CU
ATMEGA1280V-8CUR
ATMEGA2560-16CU
ATMEGA2560-16CUA0
ATMEGA2560-16CUR
ATMEGA2560-16CURA0
ATMEGA2560V-8CU
ATMEGA2560V-8CUA0
ATMEGA2560V-8CUR
ATMEGA2560V-8CURA0
ATMEGA640-16CU
ATMEGA640-16CUR
ATMEGA640V-8CU
ATMEGA640V-8CUR
ATXMEGA128A1-CU
ATXMEGA128A1-CUA1
ATXMEGA128A1-CUR
ATXMEGA128A1U-CN
ATXMEGA128A1U-CNR
ATXMEGA128A1U-CU
ATXMEGA128A1U-CUR
ATXMEGA64A1-CU
ATXMEGA64A1-CUR
ATXMEGA64A1U-CU
ATXMEGA64A1U-CUR